LESSONS FROM WATCHING PAINT DRY: film formation, moving fronts, and cracking

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OUTLINE

one-dimensional film formation

regimes temperature dependence

measurements with cantilever

capillary stresses drying fronts

cracking: theory & experiment

critical capillary pressure patterns and spacing critical thickness

Collaborators

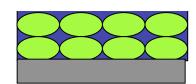
P.R. Sperry Rohm & Haas A.F. Routh *97 Cambridge Univ. M. Tirumkudulu IIT Bombay Weining Man *05

Driving Forces for Homogeneous Deformation

1. Wet sintering (Vanderhoff, 1966)

polymer/water surface tension

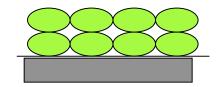
$$\frac{\gamma_{pw}}{a}$$



2. Dry sintering (Dillon, 1951)

polymer/air surface tension

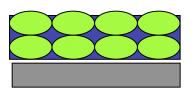
$$\frac{2\gamma_{pa}}{a}$$



3. Capillary Deformation (Brown, 1956)

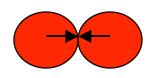
pressure at air-water interface

$$-p_{cap} = -\kappa \gamma_{wa} \le 10 - 12 \frac{\gamma_{wa}}{a}$$



In all three **negative pressure** puts the film in **tension**. The substrate prevents lateral deformation, while free surface allows **compression** in normal direction.

MODEL FOR ONE-DIMENSIONAL FILM FORMATION



$$\boldsymbol{n} \cdot \boldsymbol{\varepsilon} \cdot \boldsymbol{n} = \Delta R / R$$

$$\boldsymbol{F}_{nm} = -\frac{16}{3} a^2 \left\{ \frac{G}{2(1-v)} + \eta \frac{d}{dt} \right\} \left(-\boldsymbol{n}_{nm} \cdot \boldsymbol{\varepsilon} \cdot \boldsymbol{n}_{nm} \right)^{3/2} \boldsymbol{n}_{nm}$$

contact

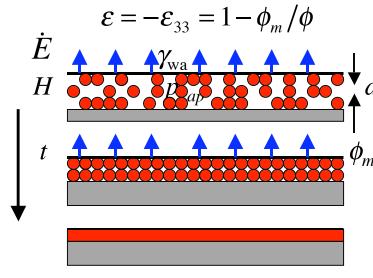
non-linear viscoelastic response

force

→ Hertzian contact (Matthews 1980)

initially isotropic thin film of close-packed spheres

$$\sigma_{33} = -p_{cap} - \frac{2}{3\pi} \phi N \left\{ \frac{G}{2(1-v)} + \eta \frac{d}{dt} \right\} \varepsilon^{3/2} = 0$$



scaling
$$\overline{t} = \dot{E}t / H \qquad \overline{\sigma}_{t} = \frac{128ap_{cap}}{15N\phi_{m}^{2}\gamma_{ma}}$$

$$\bar{G} = \frac{HG_{\infty}^{'}}{\dot{E}n}$$

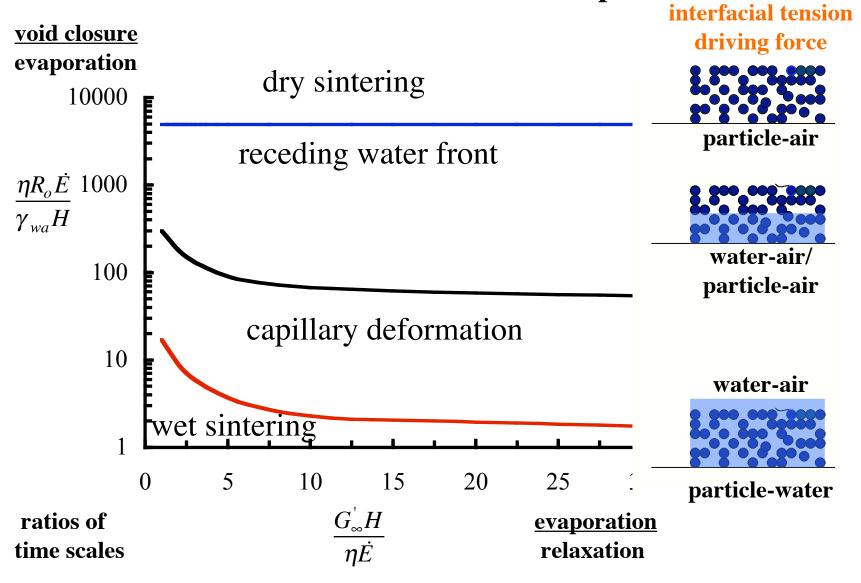
$$\overline{\lambda} = \frac{\eta a \dot{E}}{H \gamma}$$

$$\bar{\sigma}_{t} = \frac{128ap_{cap}}{15N\phi_{m}^{2}\gamma_{wa}}$$

$$\bar{G} = \frac{HG'_{\infty}}{\dot{E}\eta}$$
 evaporation time relaxation time

$$\overline{\lambda} = \frac{\eta a \dot{E}}{H \gamma_{wa}}$$
 viscous collapse time evaporation time

Generalized Process Map

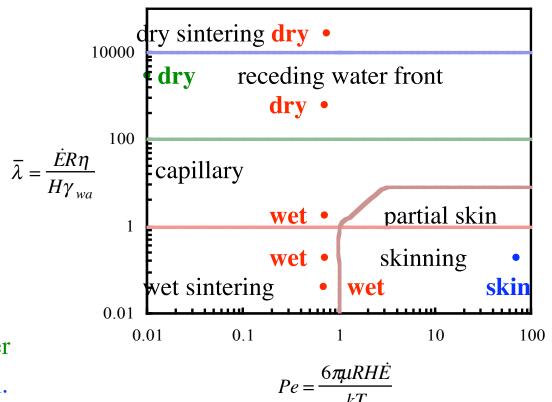


REGIMES OF DEFORMATION

key dimensionless groups

$$\bar{\lambda} = \frac{\text{time for viscous collapse}}{\text{time for evaporation}}$$

$$Pe = \frac{\text{time for evaporation}}{\text{time for diffusion}}$$



Keddie Lin & Meier Dobler et al.

EFFECT OF TEMPERATURE



 t_{comp}

wet sintering

$$0.26 \frac{\eta(T)R_o}{\gamma_{pw}}$$

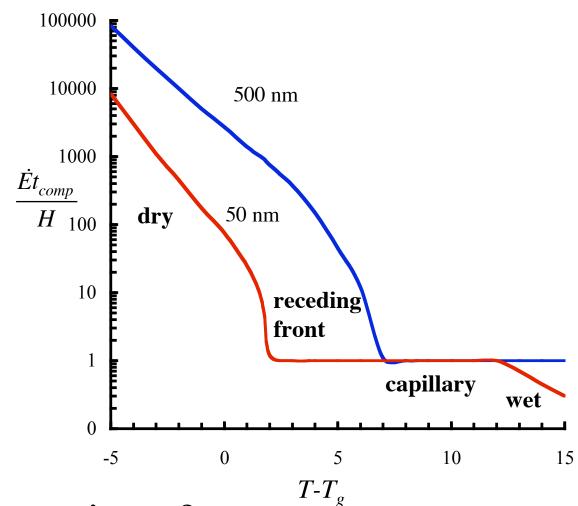
capillary

deformation

$$0.36\frac{H}{\dot{E}}$$

dry sintering

$$0.26 \frac{\eta(T)R_o}{\gamma_{pa}}$$

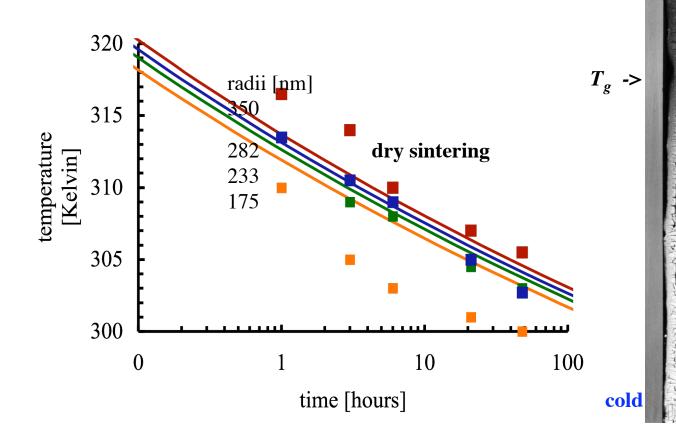


What about experiments?

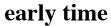
hot

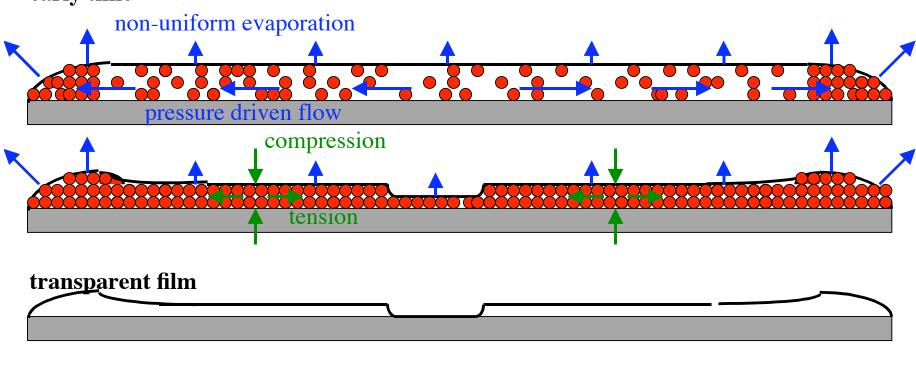
P.R. Sperry, B.S. Snyder, M.L. O'Dowd, P.M. Lesko, "Role of water in particle deformation and compaction in latex film formation" *Langmuir* **10** 2619 (1994)

minimum film formation temperature depends on glass transition temperature diameter of particles time temperature gradient bar



Film Formation, Non-Uniformities, and Cracking Driven by Capillary Pressure







Cantilever Experiment for Measuring Stresses

Chiu et al. J. Am. Ceramic Soc. (1993); Peterson, et al. Langmuir (1999); Martinez, et al. Langmuir (2000)

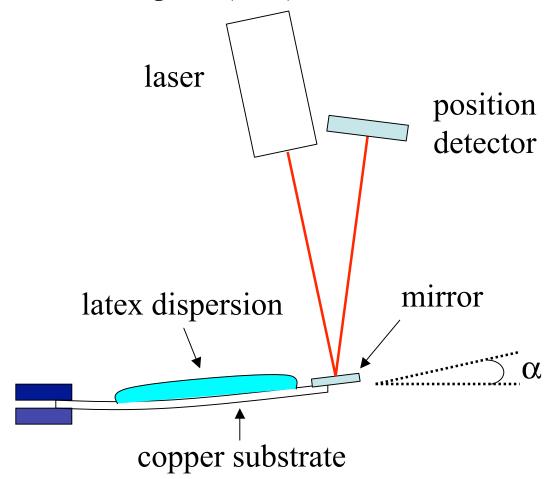
$$\sigma_{xx} = \frac{h_s^3 G\alpha}{6 L h(h + h_s)}$$

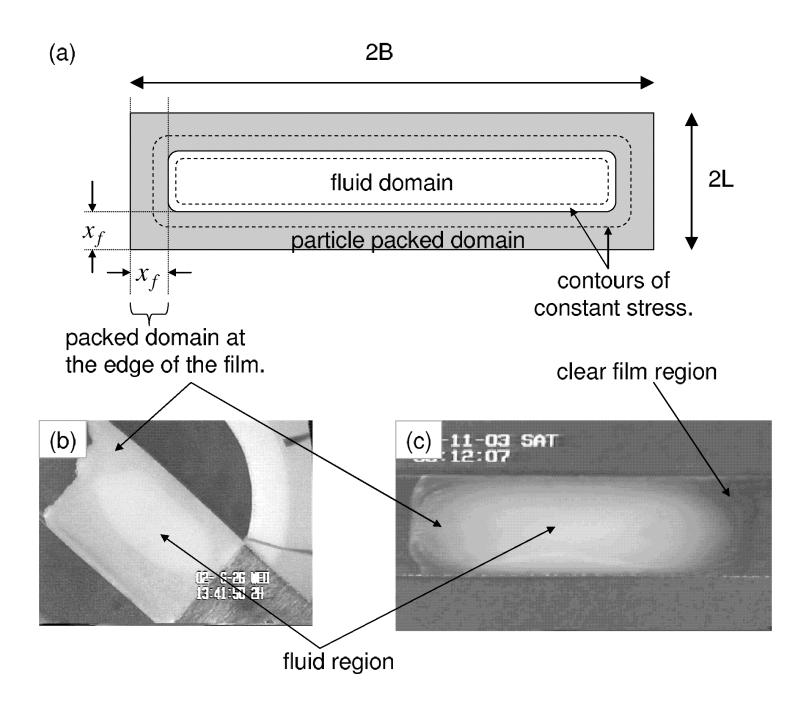
 h_s : substrate thickness

h: film thickness

L: length of film

G: bending modulus





Film forming latices

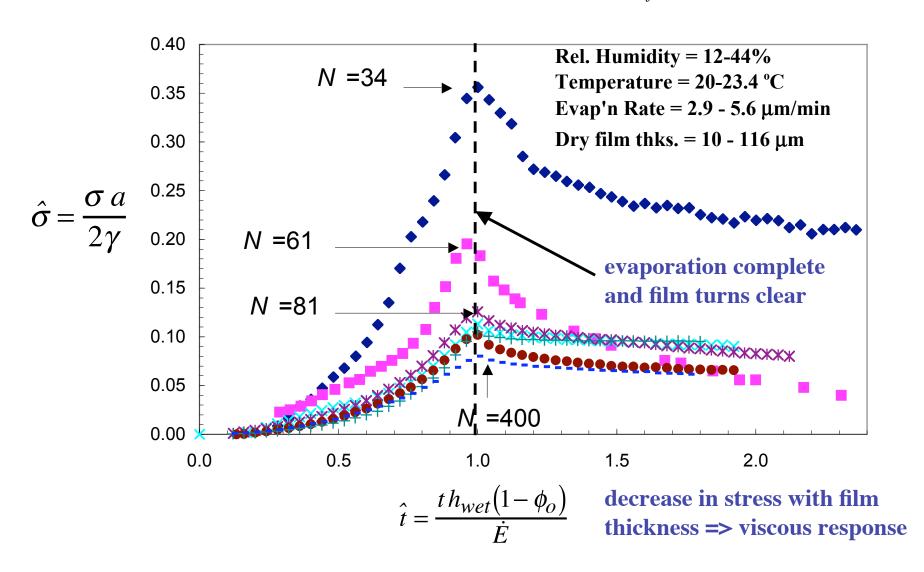
$$T_g < T_{amb}$$

Low T_g Film Forming Latex: WCFA

$$\phi_o = 0.32 - 0.35$$
 $2a = 290 \text{ nm}$ $T_{mft} = 16^{\circ}\text{C}$

$$2a = 290 \text{ nm}$$

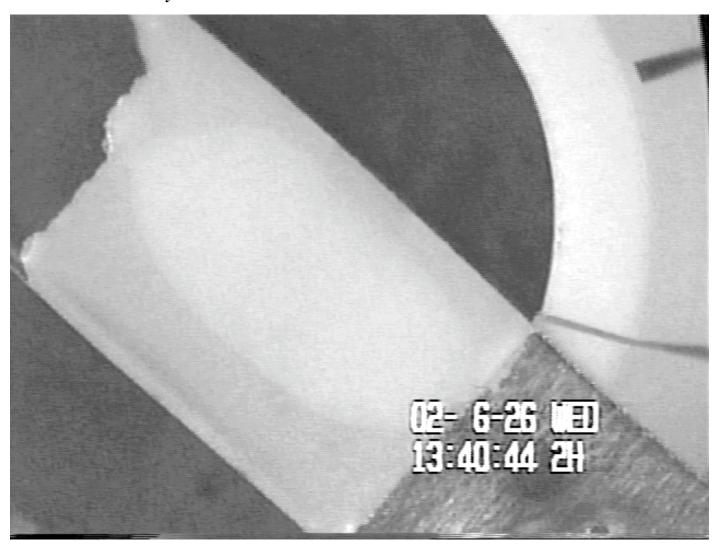
$$T_{mft} = 16^{\circ} \text{C}$$



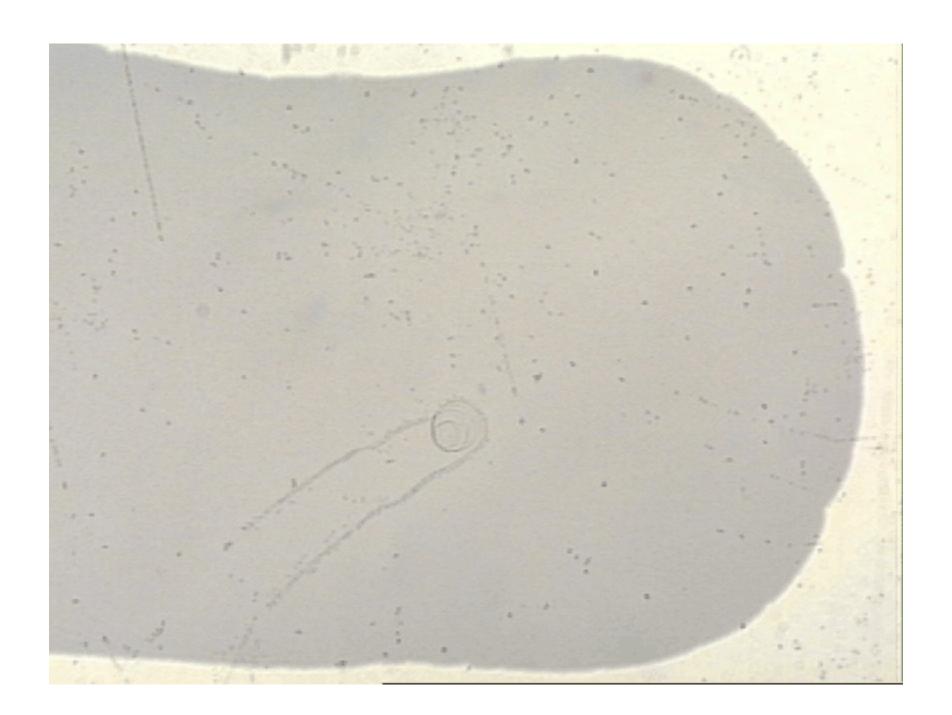
 $T_{amb} < T_g \implies$ non-film forming latices large particles => high permeability packing

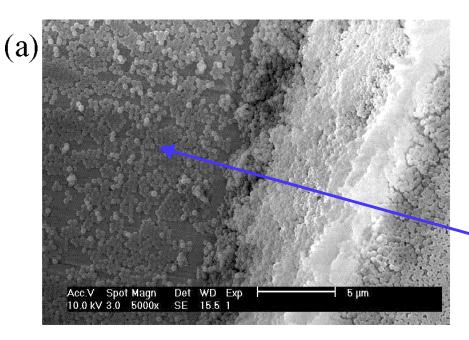
Film Cracking: Large High T_g Particles

2a=342 nm, $h_{dry}=79.5$ μ m, E=2.5 μ m/min, RH=66%, T=23.5 °C

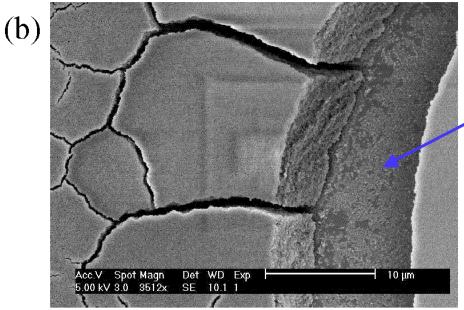


(PS342-062602b)



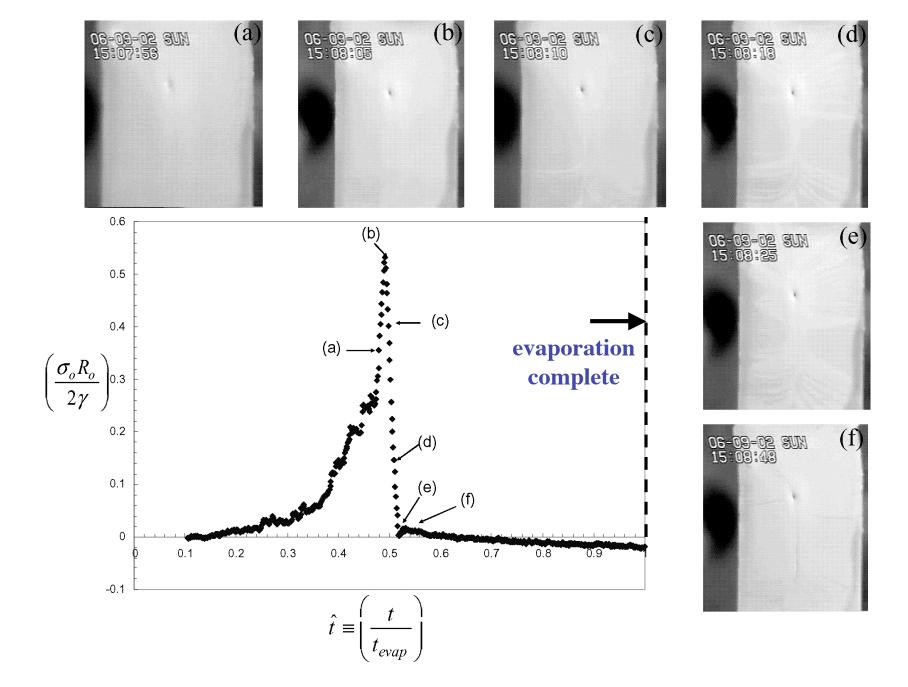


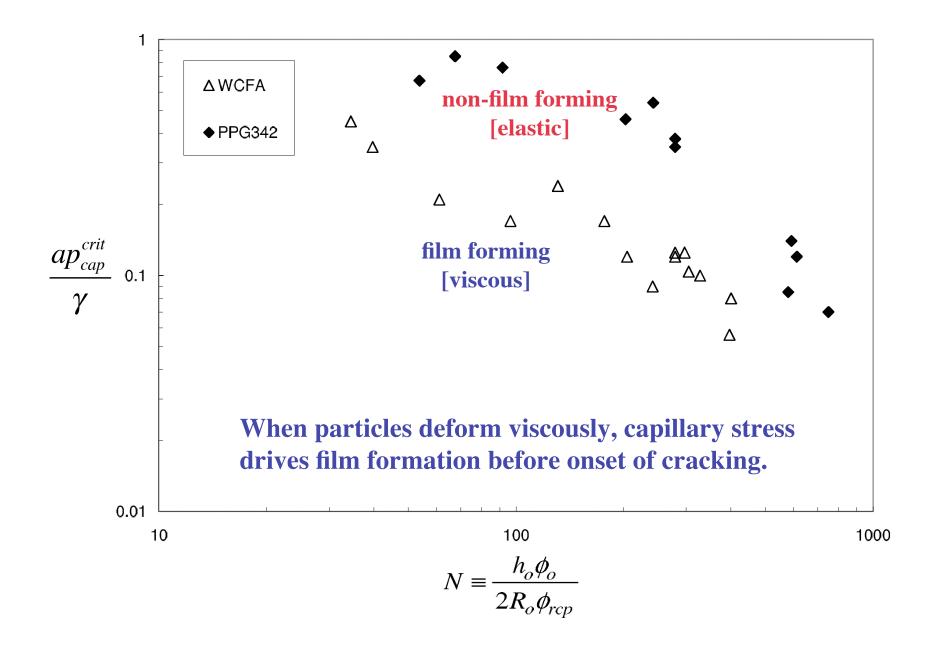
large high T_g PPG342



⇒ cracking followed by "debonding" or failure at first layer of particles

small high T_g PMMA95

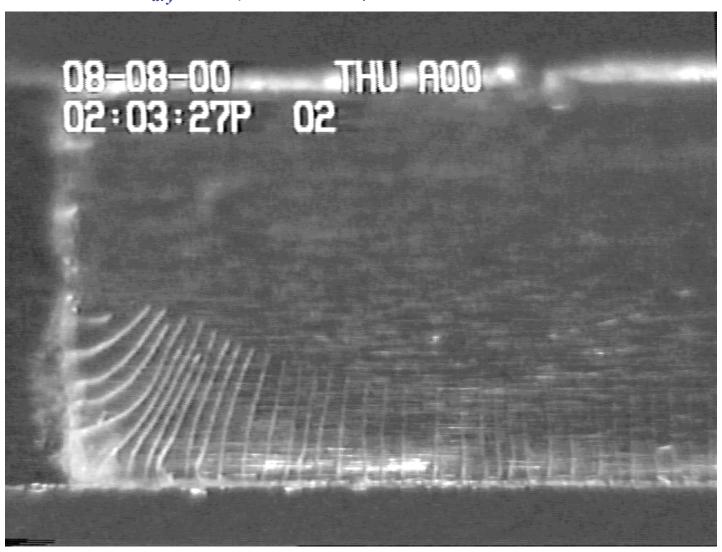




 $T_{amb} < T_g \implies$ non-film forming latices small particles => low permeability packings

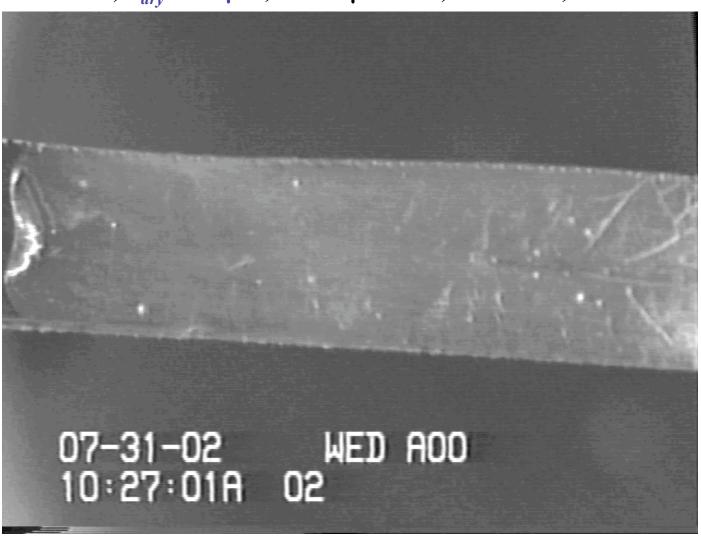
Film Cracking: Small High T_g Particles

 $2a=95 \text{ nm}, h_{dry}=101 \mu\text{m}, E=6.7 \mu\text{m/min}, RH=35\%, T=24.4 \text{ }^{\circ}\text{C}$

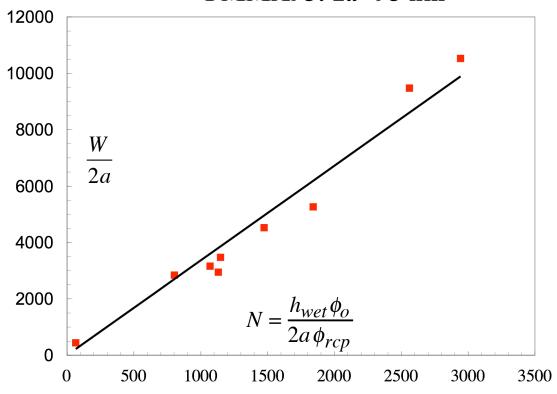


Film Cracking: Small High T_g Particles

2a=95 nm, $h_{dry}=262$ μ m, E=6.7 μ m/min, RH=35%, T=24.4 °C

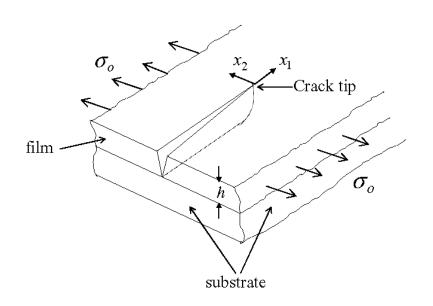


Crack Spacing PMMA95: 2*a*=95 nm



- → simple and reproducible results, but how to
 - measure in more controlled manner
 - understand the mechanism

Cracking in Thin Films



homogeneous linearly elastic films

A.G. Evans, M.D. Drory, and M.S. Hu,

J. Materials Res **3** 1043 (1988)

J.L. Beuth, *Int. J. Solids Structures* **29** 1657 (1992)

X.C. Xia and J.W. Hutchinson,

J. Mech. Phys. Solids 48 1107 (2000)

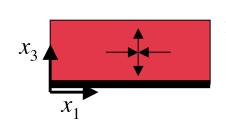
Griffiths criterion

recovery of elastic energy
$$\Delta E = h \iint \left\{ \sigma_{33} d\varepsilon_{33} + \sigma_{22} d\varepsilon_{22} + 2\sigma_{23} d\varepsilon_{23} \right\} dx_2$$

$$\parallel$$
cost of surface energy
$$2h\gamma$$

==> critical stress as function of film thickness for isolated crack spacing as function of film thickness and excess stress

• one-dimensional base state



compression normal to film

tension in plane of film

$$\sigma_{33}^{o} = -p_{o} - \frac{2}{3\pi} \phi N \frac{G}{2(1-v)} \varepsilon_{o}^{3/2} = 0$$

$$\sigma_{11}^{o} = \sigma_{22}^{o} = \frac{\phi N}{2\pi} \frac{G}{2(1-v)} \varepsilon_{o}^{3/2}$$

• two-dimensional stress fields after cracking without dilation $\varepsilon_{11}+\varepsilon_{33}=0$

stress-free air-water interface

relaxation in plane

$$\sigma'_{33} = -p' - \frac{3}{4\pi} \phi N \frac{G}{2(1-v)} \varepsilon_o^{1/2} \varepsilon'_{11} = 0$$

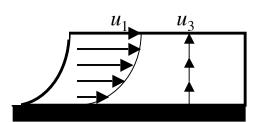
$$\Rightarrow p' = \frac{3}{4\pi} \phi N \frac{G}{2(1-v)} \varepsilon_o^{1/2} \varepsilon_{11}'$$

$$\sigma'_{11} = \frac{5}{16\pi} \phi N \frac{G}{2(1-v)} \varepsilon_o^{1/2} \varepsilon'_{11}$$

$$\sigma'_{13} = \frac{1}{2\pi} \phi N \frac{G}{2(1-v)} \varepsilon_o^{1/2} \varepsilon'_{13}$$

vertically averaged stress balance

$$\frac{\partial \left\langle \sigma_{11}^{'} \right\rangle}{\partial x_{1}} = \frac{\left. \sigma_{13}^{'} \right|_{z=0}}{h}$$



lubrication approximation $u_{1} \approx 3\langle u_{1}' \rangle \frac{x_{3}}{h} \left(1 - \frac{x_{3}}{2h} \right)$

$$\left. \varepsilon_{13}^{'} \right|_{z=0} \doteq 3 \left\langle u_{1}^{'} \right\rangle / 2h \quad \text{and} \quad \left\langle \varepsilon_{13}^{'} \right\rangle \doteq 3 \left\langle u_{1}^{'} \right\rangle / 4h$$

equation for displacement

$$\frac{\partial^{2} \left\langle u_{1}^{'} \right\rangle}{\partial x_{1}^{2}} = \frac{6}{7} \frac{\left\langle u_{1}^{'} \right\rangle}{h^{2}} \quad \text{with} \quad \varepsilon_{o} + \frac{7}{4} \frac{\partial \left\langle u_{1}^{'} \right\rangle}{\partial x_{1}} (0) = 0 \qquad \left\langle u_{1}^{'} \right\rangle (\infty) = 0$$

$$\text{stress-free crack} \quad \text{uniform film}$$

$$\text{surface}$$

- solve boundary value problems
- integrate to evaluate recovery of elastic energy
- equate to surface energy

critical stress for isolated crack

$$\frac{p_{cap}^{crit}a}{\gamma} = 1.17 \left(\frac{a}{h}\right)^{3/5} \left(\frac{GN\phi_o a}{(1-v)\gamma}\right)^{2/5} \implies \frac{p_{cap}^{crit}h}{\gamma} = 2.0 \left(\frac{Gh}{(1-v)\gamma}\right)^{2/5}$$

spacing W between parallel cracks as function of excess stress

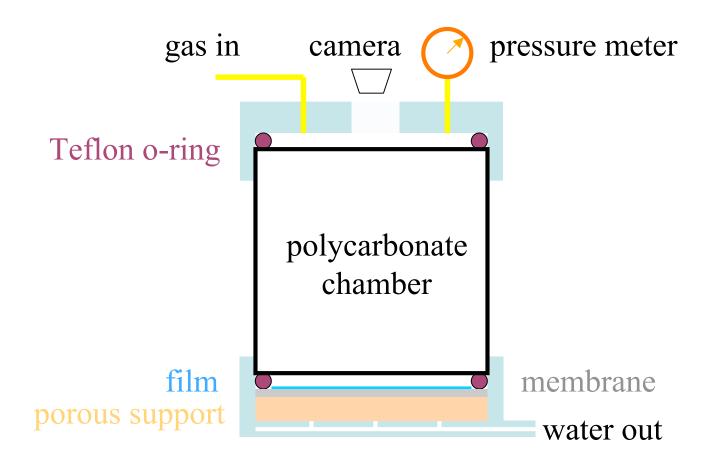
$$\frac{p_{cap}^{crit}}{p_{cap}} = \left\{ \frac{3}{8} \tanh\left(\sqrt{\frac{6}{7}} \frac{W}{2h}\right) - \left[5\sinh\left(\sqrt{\frac{6}{7}} \frac{W}{h}\right) - \sqrt{\frac{6}{7}} \frac{W}{h}\right] \right/ 6\cosh^2\left(\sqrt{\frac{6}{7}} \frac{W}{2h}\right) \right\}^{3/5}$$

minimum thickness for cracking $p_{cap}^{crit} = 10\gamma/a$

$$\frac{h_{crit}}{a} = 0.068 \left(\frac{Ga}{(1-v)\gamma}\right)^{2/3}$$

Direct Measurement of Stresses

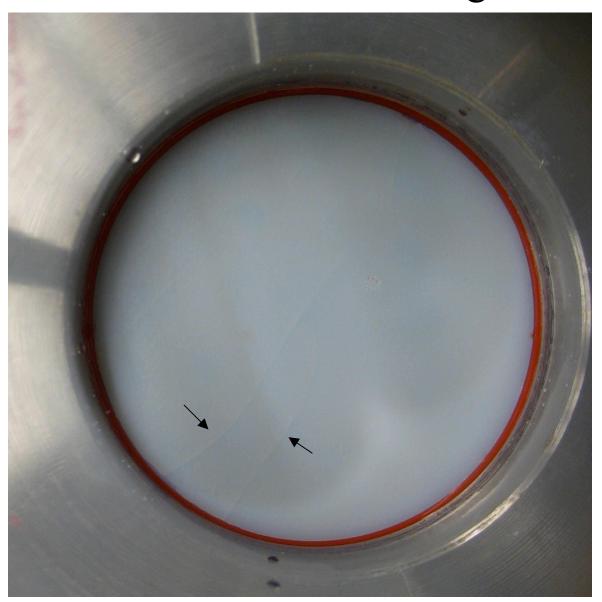
high pressure filter chamber:



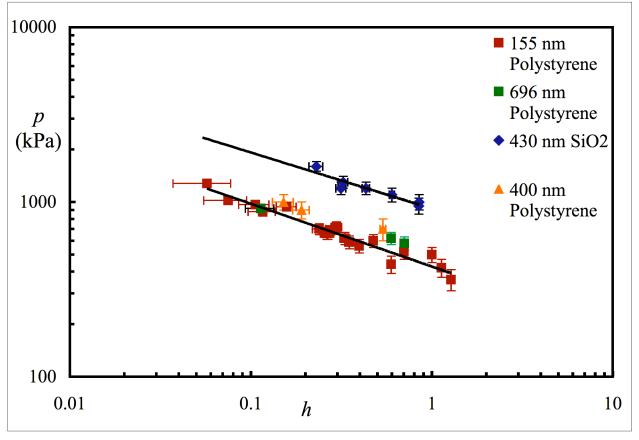
Experimental Procedure

- Dispersions consist of polymer latices below T_g or silica.
- Push water out slowly at low pressure (50 kPa) to create close packing.
- Water vapor saturates air inside the chamber, stopping evaporation.
- Gradually increase pressure until the film cracks to determine directly the critical capillary pressure.
- Continue increasing pressure in steps and photograph cracks to determine dependence of crack spacing on pressure.
- Remove film and weigh while still wet and then after drying to determine volume fraction and thickness of film.

Film as onset of cracking



Parametric Dependence of Cracking Stress



→ cracking pressure independent of particle radius

variables

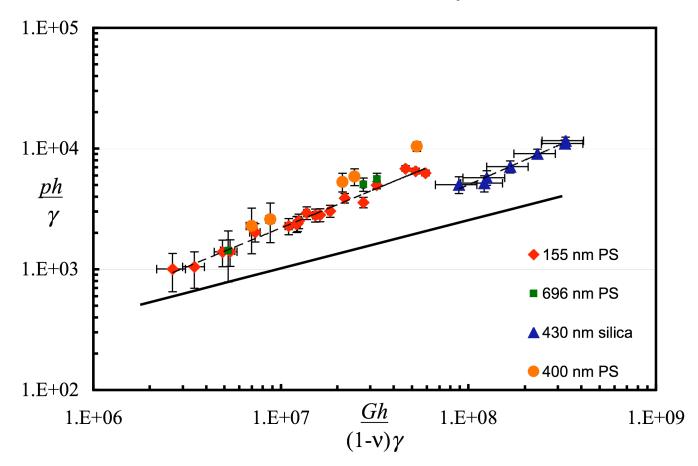
$$p$$
 kg/m-s
 h m
 γ kg/s
 $G/(1-v)$ kg/m-s

dimensional analysis

⇒ two dimensionless variables one a function of the other $\frac{ph}{\gamma} = f\left(\frac{Gh}{(1-v)\gamma}\right)$

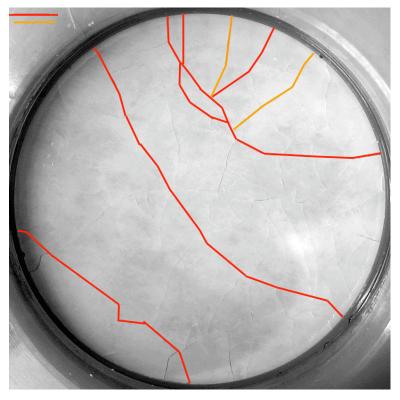
$$\frac{ph}{\gamma} = f\left(\frac{Gh}{(1-v)\gamma}\right)$$

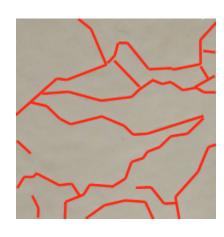
Dimensional Analysis



Balancing elastic energy recovered by cracking against the additional surface energy (———) provides **lower bound** on capillary pressure that produces cracking.

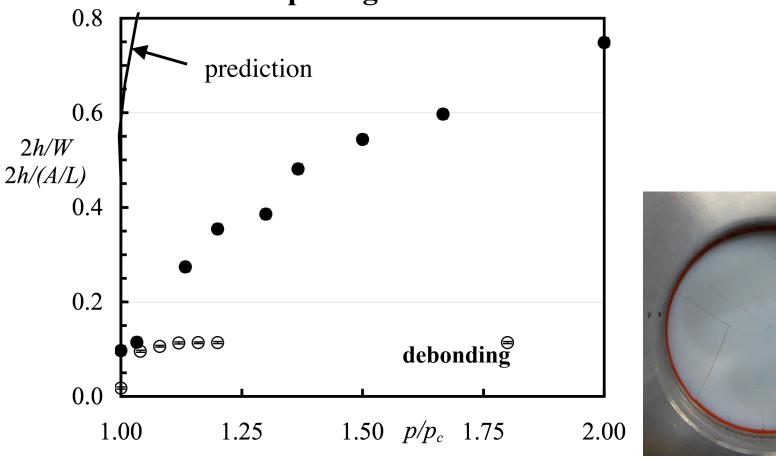
Cracking spacing at pressures above p_{crit}





A =area of film L =total length of cracks parallel cracks W=A/L orthogonal cracks W=2A/L triangular cracks W=3A/L

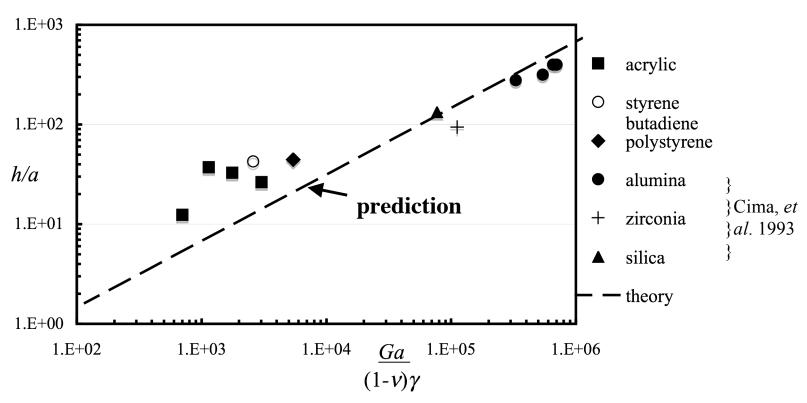
Normalized spacing as function of excess stress



- Debonding terminates cracking by relaxing stress.
- Theory for parallel cracks misses phenomenon.
- → Subsequent cracking controlled by distribution of flaws?

Critical Thickness via Spin Coating

K.B. Singh & M.S. Tirumkudulu (in preparation)



hypothesis: When capillary pressure exceeds $10\gamma/a$ without causing cracking, the water front simply recedes into film.

$$\frac{10\gamma}{a} \times \frac{h}{\gamma} = 2\left(\frac{Gh}{(1-v)\gamma}\right)^{2/5} \rightarrow \frac{h_{crit}}{a} = 0.068 \left(\frac{Ga}{(1-v)\gamma}\right)^{2/3}$$

SUMMARY

- Mode of film formation depends on rate of evaporation relative to rate of viscous deformation driven by capillary pressure.
- Edges cause gradients in capillary pressure that draw fluid from the center to sustain mass transfer limited evaporation.
- Particles that deform too slowly allow the capillary pressure to cause cracking before the water front recedes into the film.
- The capillary pressure required for cracking decreases with increasing film thickness and elastic compliance but is independent of particle size. The density of cracks increases with with excess pressure but appears to be nucleation controlled.
- There exists a thickness below which films of even hard particles do not crack.